

REMARKS

Claim 1 has been amended to specify that the spring contact contacts a first side of the wafer and the base seals a second side of the wafer opposite the first side.


In the cited reference to Brogden, the seal 40 and the contacts 36 contact the same side of the wafer. Supplying the dispersed contacting apparatus of Jorné to the device of Brogden still fails to meet the requirement of the claim that the sealing contact and the electrical contact be on opposite sides.

Moreover, it creates the apparently insoluble problem in Brogden as to how one is to provide the apparatus 32 of Jorné in the apparatus of Brogden when doing so would apparently require violating the seal 40 and thereby counteracting the sealing effect of the seal 40. In other words, there is no way to get to the other side of the seal 40 except to go through it, which then breaks the seal.

Since the proposed combination does not work and still fails to meet the claimed limitations, reconsideration would be appropriate.

Respectfully submitted,

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